TI Collaborates with Microsoft to Kickstart Development of IoT Applications



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Microsoft Azure has established itself as one of the leading public cloud platforms in the industry. Continuing its innovation in Internet of Things (IoT) applications. Today, Microsoft launched Microsoft Azure IoT Suite and Microsoft Azure Certified for IoT, featuring TI as an initial member. Microsoft Azure Certified for IoT involves verification that devices are compatible with the Azure IoT Suite to enable developers who have purchased TI's low-cost development kits to easily download the appropriate Microsoft Azure for IoT agent to quickly connect to the cloud.



TI offers the broadest portfolio of devices in the industry for IoT node and gateway applications. As a result, TI and Microsoft have collaborated to certify multiple TI devices, with more to follow. The first set includes:

- SimpleLink Wi-Fi CC3200 wireless MCU LaunchPad kit enables a low power and secure connection to the cloud
- BeagleBone Black board based on Ti's Sitara AM335x processor with a 1GHz ARM® Cortex®-A8 core supports Ethernet as well as Wi-Fi connectivity through Ti's WiLinkTM 8 Wi-Fi + Bluetooth ® combo connectivity modules.
- SeeedStudio BeagleBone Green board based on the BeagleBone Black is specially designed for rapid
 prototyping and deployment of IoT applications and features built-in GROVE module connections, allowing
 developers to snap in a wide range of sensors and analog input devices.

For the BeagleBone platforms, the Node.js Azure IoT SDK is supported. The SimpleLink Wi-Fi CC3200 wireless MCU use the C Azure IoT SDK. The embedded SDKs use the MIT open-source license and can be downloaded at https://github.com/Azure/azure-iot-sdks.

The certified devices enable developers to immediately connect their board to Azure IoT Suite and begin application development immediately. There is no need to spend days, weeks or months bringing up your connection to the cloud.

Get started today!

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